



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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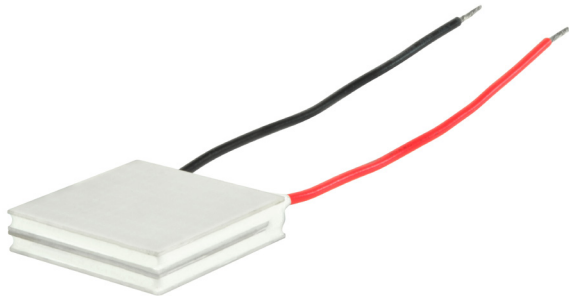
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



SERIES: CP36H-2 | **DESCRIPTION:** PELTIER MODULE

FEATURES

- arcTEC™ structure
- solid state device
- 2-stage cooler
- precise temperature control
- silent operation



MODEL

MODEL	input voltage ¹ max (Vdc)	input current ² max (A)	internal resistance ³ typ (Ω±10%)	output Qmax ⁴		output ΔTmax ⁵	
				T _h =27°C (W)	T _h =50°C (W)	T _h =27°C (°C)	T _h =50°C (°C)
CP36367H-2	16.7	3.6	4.43	21	23	82	92

- Notes:
1. Maximum voltage at ΔT max and T_h=27°C
 2. Maximum current to achieve ΔT max
 3. Measured by AC 4-terminal method at 25°C
 4. Maximum heat absorbed at cold side occurs at I_{max}, V_{max} and ΔT=0°C
 5. Maximum temperature difference occurs at I_{max}, V_{max} and Q=0W (ΔT max measured in a vacuum at 1.3 Pa)

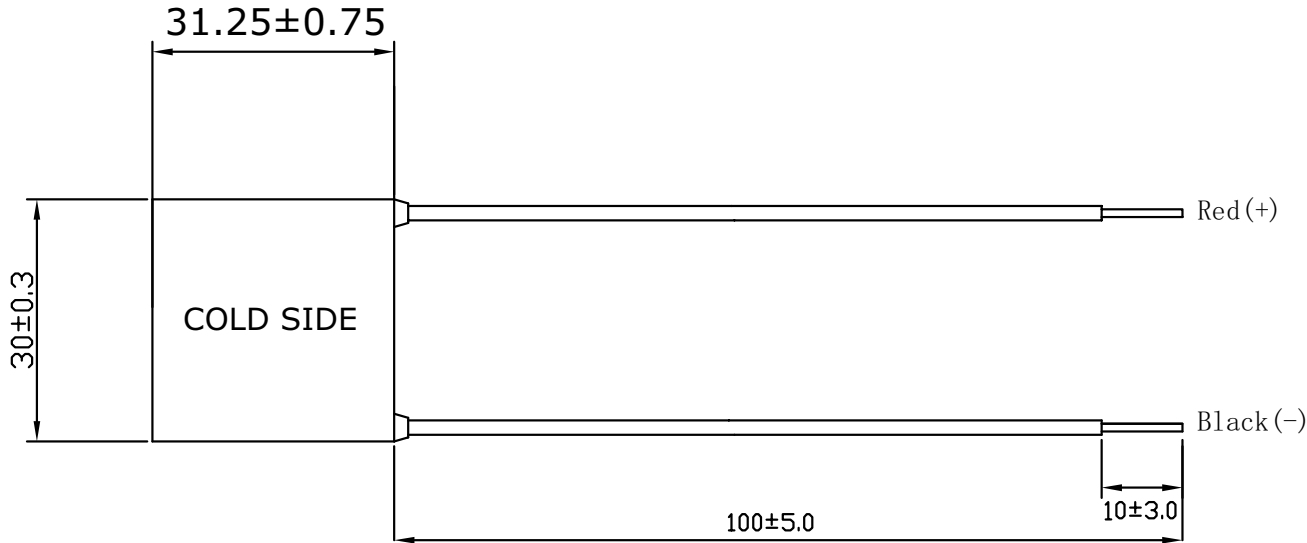
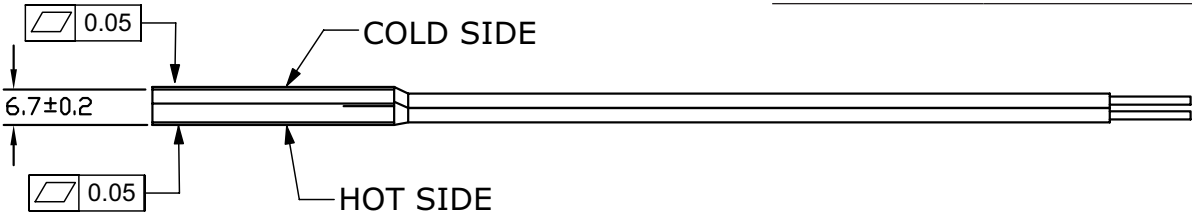
SPECIFICATIONS

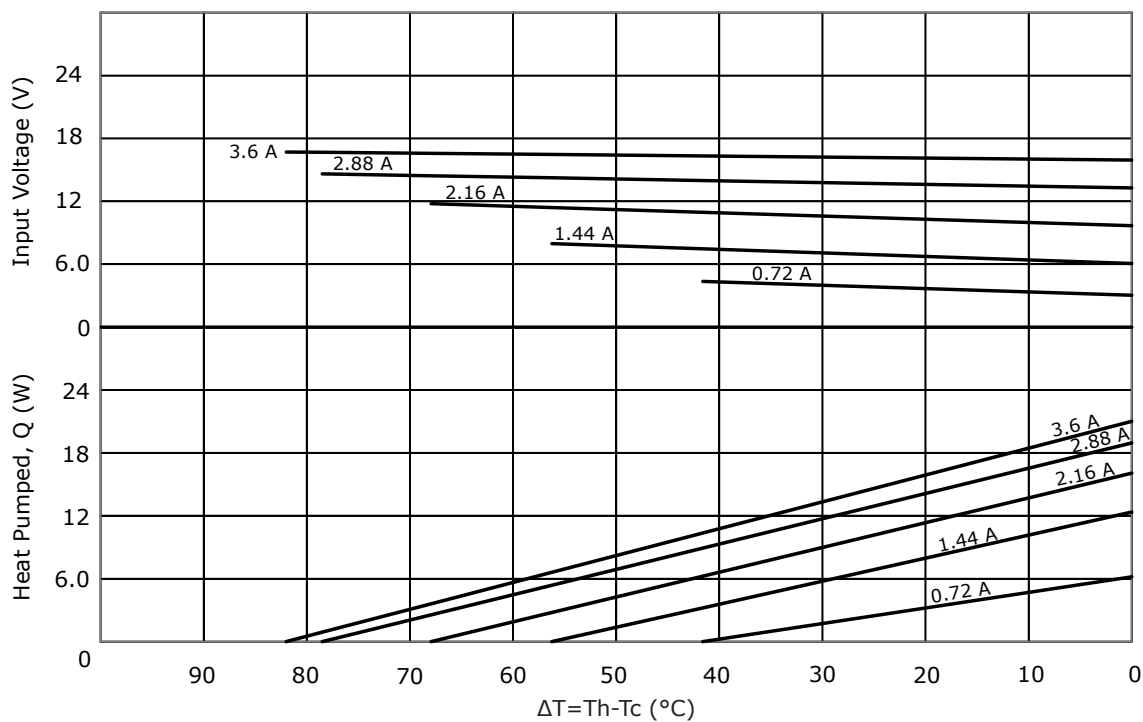
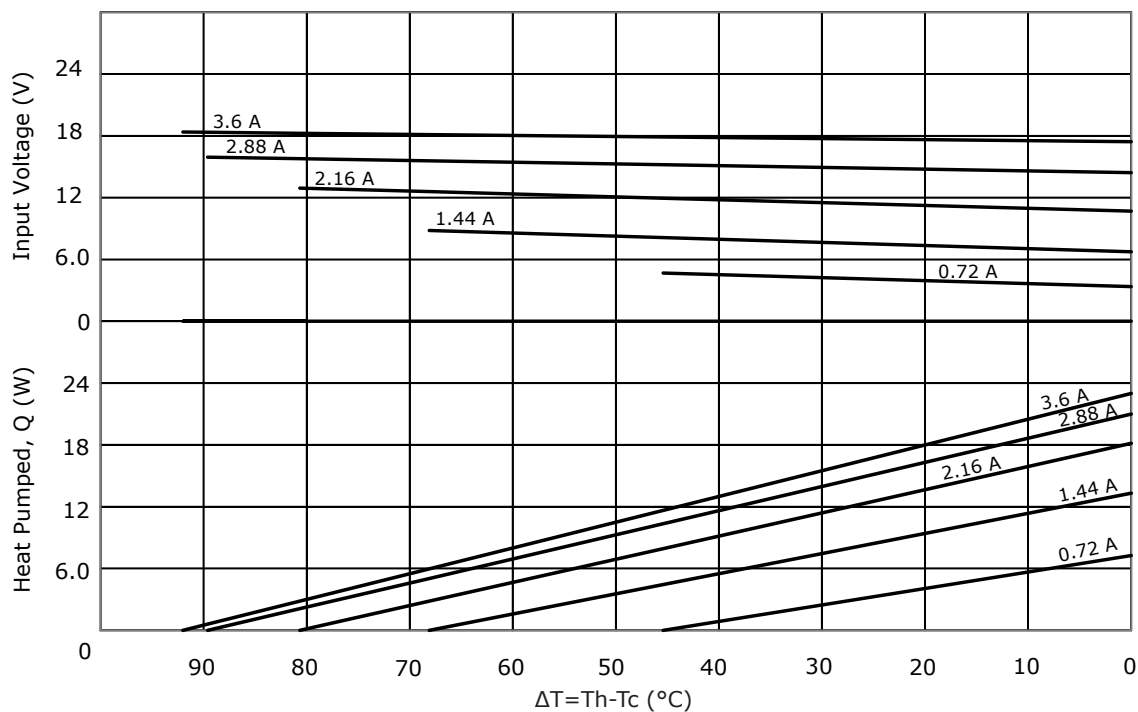
parameter	conditions/description	min	typ	max	units
solder melting temperature	connection between thermoelectric pairs	235			°C
assembly compression				1	MPa
hot side plate				100	°C
RoHS	2011/65/EU				

MECHANICAL DRAWING

units: mm

	MATERIAL	PLATING
ceramic plate	96% AL_2O_3	
wire leads	20 AWG	tin
sealer	silicon rubber 703 RTV (between cold and hot side plates)	
joint cover	silicon rubber 703 RTV	
marking	P/N & S/N printed on cold side surface	



PERFORMANCE (Th=27°C)**PERFORMANCE (Th=50°C)**

REVISION HISTORY

rev.	description	date
1.0	initial release	05/21/2018

The revision history provided is for informational purposes only and is believed to be accurate.



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